

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







Preferred Device

SWITCHMODE™ Power Rectifier

D²PAK Surface Mount Power Package

The D²PAK Power Rectifier is a state-of-the-art device that employs the Schottky Barrier principle with a platinum barrier metal.

Features

- Center-Tap Configuration
- Guardring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured Not Sheared
- Similar in Size to the Industry Standard TO-220 Package
- Pb-Free Packages are Available

Mechanical Characteristics

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V)

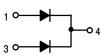
Human Body Model, 3B (>8000 V)

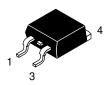


ON Semiconductor®

http://onsemi.com

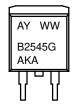
SCHOTTKY BARRIER RECTIFIER 30 AMPERES, 45 VOLTS





D²PAK CASE 418B STYLE 3

MARKING DIAGRAM



A = Assembly Location

Y = Year
WW = Work Week
B2545 = Device Code
G = Pb-Free Package
AKA = Diode Polarity

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

MAXIMUM RATINGS (Per Leg)

| Rating | Symbol | Value | Unit |
|-------------------------------------------------------------------------------------------------------------|--------------------------------------------------------|-------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 45 | V |
| Average Rectified Forward Current (Rated V_R , $T_C = 164$ °C) Total Device | I _{F(AV)} | 15 30 | А |
| Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, $T_C = 160^{\circ}C$) | I _{FRM} | 30 | А |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I _{FSM} | 150 | А |
| Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz) | I _{RRM} | 1.0 | Α |
| Storage Temperature Range | T _{stg} | -65 to +175 | °C |
| Operating Junction Temperature (Note 1) | T _J | -65 to +175 | °C |
| Voltage Rate of Change (Rated V _R) | dv/dt | 10,000 | V/μs |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS (Per Leg)

| Characteristic | | Value | Unit |
|-----------------------------------------------------------------------|--------------------------------------------------------|-----------|------|
| Thermal Resistance, – Junction-to-Case – Junction-to-Ambient (Note 2) | $egin{array}{l} R_{	hetaJC} \ R_{	hetaJA} \end{array}$ | 1.5 50 | °C/W |

^{2.} When mounted using minimum recommended pad size on FR-4 board.

ELECTRICAL CHARACTERISTICS (Per Diode)

| Symbol | Characteristic | Condition | Min | Тур | Max | Unit |
|----------------|-------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------|------------------------|------------------------------|------|
| V _F | Instantaneous Forward Voltage (Note 3) | $\begin{array}{c} I_F = 15 \text{ Amp, } T_J = 25^{\circ}\text{C} \\ I_F = 15 \text{ Amp, } T_J = 125^{\circ}\text{C} \\ I_F = 30 \text{ Amp, } T_J = 25^{\circ}\text{C} \\ I_F = 30 \text{ Amp, } T_J = 125^{\circ}\text{C} \end{array}$ | - - - - | - 0.50 - 0.65 | 0.62 0.57 0.82 0.72 | V |
| I _R | Instantaneous Reverse Current (Note 3) | $V_R = 45 \text{ Volts}, T_J = 25^{\circ}\text{C}$ $V_R = 45 \text{ Volts}, T_J = 125^{\circ}\text{C}$ | - | 9.0 | 0.2 25 | mA |

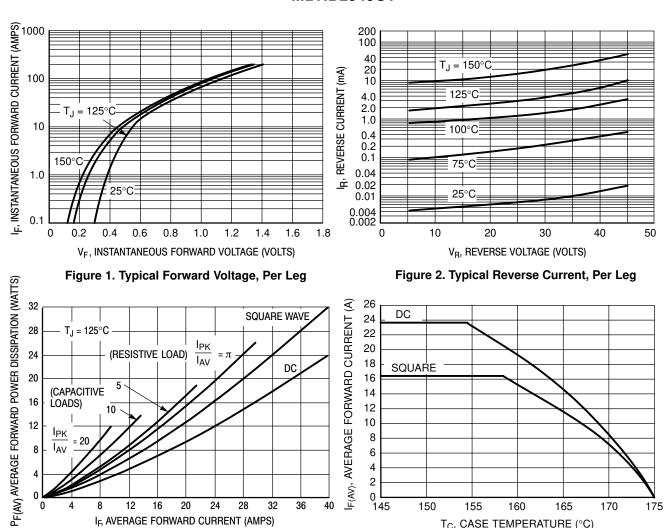
^{3.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|---------------|---------------------------------|-------------------------|
| MBRB2545CT | D ² PAK | 50 Units / Rail |
| MBRB2545CTG | D ² PAK (Pb-Free) | 50 Units / Rail |
| MBRB2545CTT4 | D ² PAK | 800 Units / Tape & Reel |
| MBRB2545CTT4G | D ² PAK (Pb-Free) | 800 Units / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{1.} The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.



IF, AVERAGE FORWARD CURRENT (AMPS) Figure 3. Typical Forward Power Dissipation

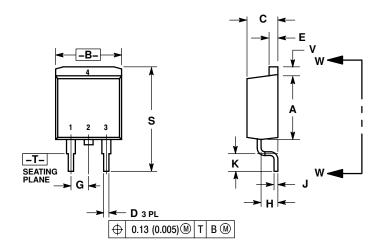
 I_{AV}

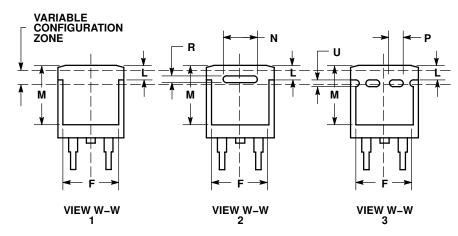
Figure 4. Current Derating, Case per Leg

T_C, CASE TEMPERATURE (°C)

PACKAGE DIMENSIONS

D²PAK 3 CASE 418B-04 ISSUE J



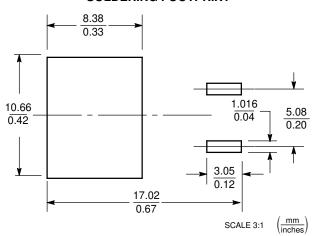


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

| | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.340 | 0.380 | 8.64 | 9.65 |
| В | 0.380 | 0.405 | 9.65 | 10.29 |
| С | 0.160 | 0.190 | 4.06 | 4.83 |
| D | 0.020 | 0.035 | 0.51 | 0.89 |
| E | 0.045 | 0.055 | 1.14 | 1.40 |
| F | 0.310 | 0.350 | 7.87 | 8.89 |
| G | 0.100 BSC | | 2.54 BSC | |
| Н | 0.080 | 0.110 | 2.03 | 2.79 |
| J | 0.018 | 0.025 | 0.46 | 0.64 |
| K | 0.090 | 0.110 | 2.29 | 2.79 |
| L | 0.052 | 0.072 | 1.32 | 1.83 |
| M | 0.280 | 0.320 | 7.11 | 8.13 |
| N | 0.197 REF | | 5.00 REF | |
| Р | 0.079 REF | | 2.00 REF | |
| R | 0.039 REF | | 0.99 REF | |
| S | 0.575 | 0.625 | 14.60 | 15.88 |
| V | 0.045 | 0.055 | 1.14 | 1.40 |

STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SWITCHMODE is a trademark of Semiconductor Components Industries, LLC.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative